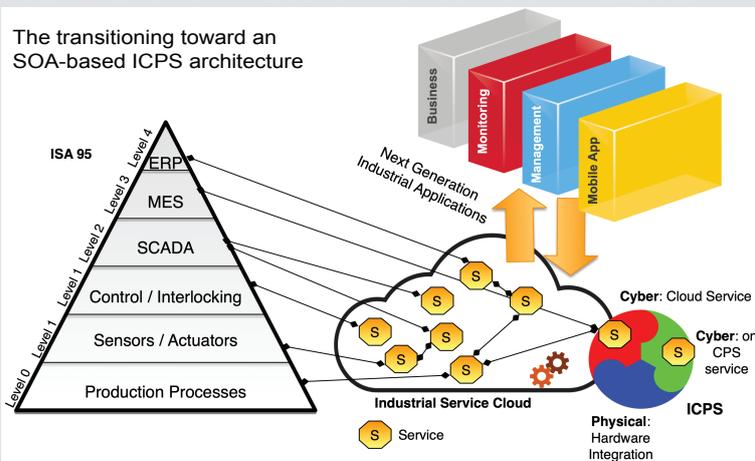


# IEEE Transactions on Industrial Cyber-Physical Systems

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The transitioning toward an SOA-based ICPS architecture



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